

Thermally-Enhanced High Power RF GaN HEMT 70 W, 50 V, 1805 – 2170 MHz

Description

The GTVA220701FA is a 70-watt (P_{3dB}) GaN high electron mobility transistor (HEMT) for use in multi-standard cellular power amplifier applications. It features input matching, high efficiency, and a thermally-enhanced package with earless flange.

Advance Specification Data Sheets describe products that are being considered by Infineon for development and market introduction. The target performance shown in Advance Specifications is not final and should not be used for any design activity. Please contact Infineon about the future availability of these products.

Features

- Input matched
- Typical Pulsed CW performance, 2170 MHz, 48 V
 - Output power at P_{3dB} = 70 W
 - Efficiency = 70%
 - Gain = 20 dB
- Capable of handling 10:1 VSWR @48 V, 70 W (CW) output power
- GaN HEMT technology
- High power density
- High efficiency
- RoHS-compliant



GTVA220701FA
Package H-37265J-2

advance specification

Target RF Characteristics

Single-carrier LTE Specifications (tested in Infineon test fixture)

V_{DD} = 48 V, I_{DQ} = 200 mA, P_{OUT} = 6.3 W avg, f_1 = 2170 MHz, 3GPP signal, channel bandwidth = 20 MHz, peak/average = 9.6 dB @ 0.01% CCDF

Characteristic	Symbol	Min	Typ	Max	Unit
Linear Gain	G_{ps}	—	21.3	—	dB
Drain Efficiency	η_D	—	26	—	%
Adjacent Channel Power Ratio	ACPR	—	-29.6	—	dBc

All published data at $T_{CASE} = 25^\circ C$ unless otherwise indicated

ESD: Electrostatic discharge sensitive device—observe handling precautions!

DC Characteristics (measured on wafer prior to packaging)

Characteristic	Conditions	Symbol	Min	Typ	Max	Unit
Drain-source Breakdown Voltage	$V_{GS} = -8\text{ V}$, $I_D = 32\text{ mA}$	$V_{(BR)DSS}$	150	—	—	V
Gate Threshold Voltage	$V_{DS} = 10\text{ V}$, $I_D = 32\text{ mA}$	$V_{GS(th)}$	-3.8	-3.0	-2.3	V
Gate Quiescent Voltage	$V_{DS} = 50\text{ V}$, $I_D = 0.2\text{ A}$	$V_{GS(Q)}$	—	-2.8	—	V
Saturated Drain Current	$V_{DS} = 6\text{ V}$, $V_{GS} = 2\text{ V}$	I_{DS}	9.6	11.5	—	A

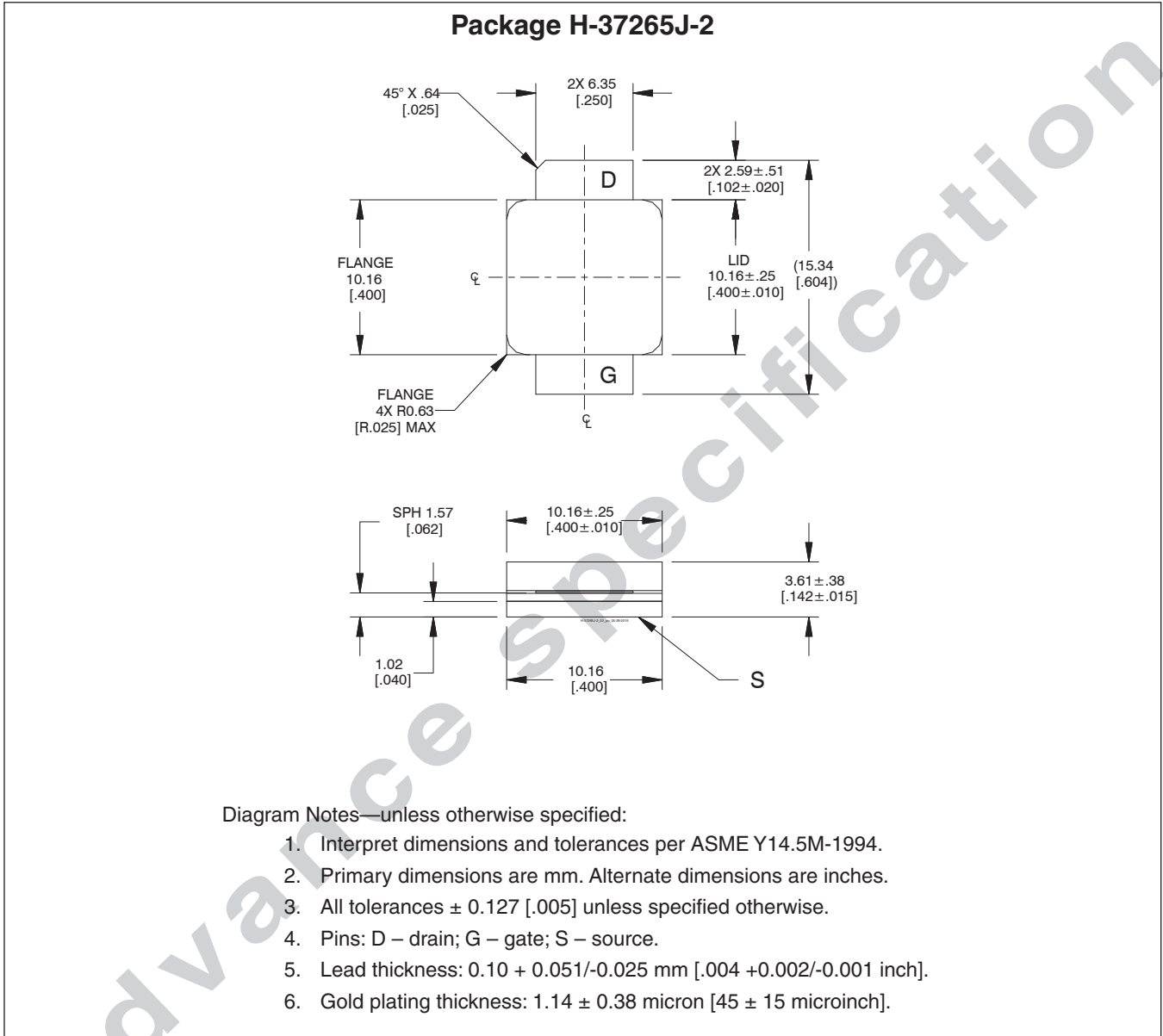
Maximum Ratings

Parameter	Symbol	Value	Unit
Drain-source Voltage	V_{DSS}	125	V
Gate-source Voltage	V_{GS}	-10 to +2	V
Operating Voltage	V_{DD}	0 to +50	V
Gate Current	I_G	20	mA
Drain Current	I_D	13.5	A
Junction Temperature	T_J	225	°C
Storage Temperature Range	T_{STG}	-65 to +150	°C
Thermal Resistance	$R_{\theta JC}$	TBD	°C/W

Ordering Information

Type and Version	Order Code	Package Description	Shipping
GTVA220701FA V1 R0	TBD	H-37265J-2, earless flange	Tape & Reel, 50 pcs
GTVA220701FA V1 R2	TBD	H-37265J-2, earless flange	Tape & Reel, 250 pcs

Package Outline Specifications



Find the latest and most complete information about products and packaging at the Infineon Internet page <http://www.infineon.com/rfpower>

Revision History

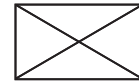
Revision	Date	Data Sheet Type	Page	Subjects (major changes since last revision)
01	2015-08-18	Advance	All	Data Sheet reflects advance specification for product development

We Listen to Your Comments

Any information within this document that you feel is wrong, unclear or missing at all? Your feedback will help us to continuously improve the quality of this document. Please send your proposal (including a reference to this document) to:

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For further information on technology, delivery terms and conditions and prices, please contact the nearest Infineon Technologies Office (www.infineon.com/rfpower).

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